



# **CORPORATE OVERVIEW 2023**

## **CONNECTING THE WORLD**

Silicon | Systems | Software | IoT

# OVERVIEW

Established in  
1999, with 20+  
years of  
expertise

Developed and  
shipped millions  
of connectivity  
ASICs over the  
years

Focused on Product  
Engineering in  
Mixed signal IP,  
Turnkey ASICs,  
Semiconductor and  
IOT solutions

1300+ engineers  
spread across  
Silicon valley – USA,  
Hyderabad,  
Bangalore,  
Ahmedabad & Pune

Domain expertise in IoT,  
Consumer, Multimedia,  
Automotive, Networking  
& Telecommunications,  
Handheld, Storage, Edge  
Applications

**“We are one of the versatile organizations with solutions & services for almost every industry” – CEO**

# BUSINESS UNITS

## Semiconductors

### Semiconductor IP

- Digital IP
- Verification IP
- SerDes IP
- ADC / DAC IP
- PLL IP

### Semiconductor Design Services

- RTL design & verification Services
- Analog layout services
- Physical design services

### Turn-key ASIC

- RTL to Volume Production
- Working relationship with leading fabs
- Successful track record

## Embedded System & Software Design

### Product / System Design

- High Speed Product & System Design
- Platform Designs with FPGA, SoC & ASIC's
- DFM / DFA, & EMS
- Platform Bring-up & Validation



### Embedded Software

- OS Porting & Board Support Package
- Device Drivers – Bare metal, OS
- Software Integration
- Software Testing
- Software maintenance/ support

**ISO 9001:2015 certification for SoC Design, Development, Assembly, Supply & Services of Semiconductors, Software & Systems**

# LOCATIONS



-  **Global Headquarters**
-  **Subsidiary / Branch Office**

# TECHNOLOGY ALLIANCES

**FPGA DESIGN PARTNER**



[Click Here to View Details](#)

**CERTIFIED ALLIANCE  
MEMBER**



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**SENSAI MEMBER**



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**BUILD PARTNER**



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## FOUNDRIY ALLIANCE – TSMC DCA PARTNER



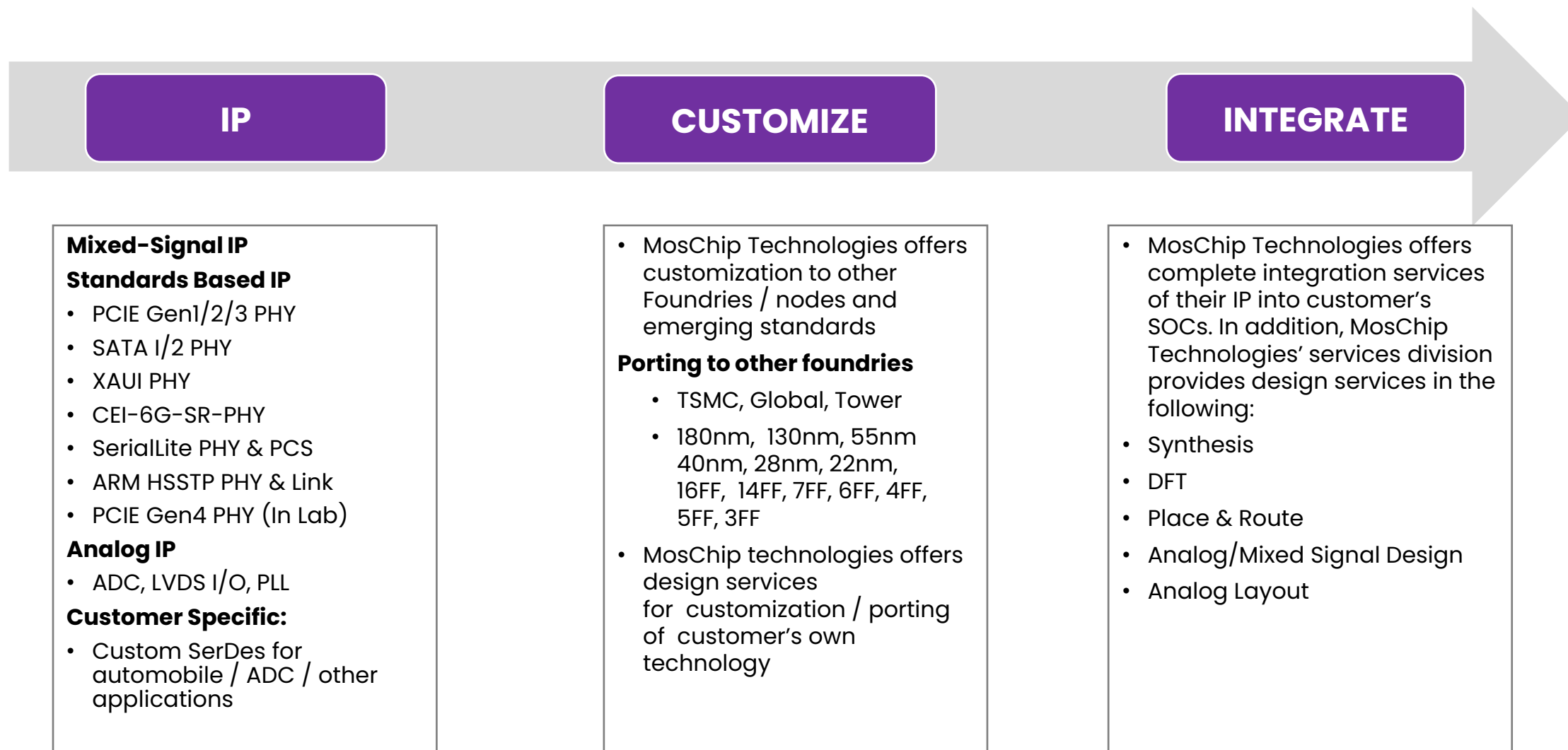
"We're very pleased with the addition of MosChip to our OIP Design Center Alliance to address the growing market need for design services on TSMC's industry-leading technologies," said **Dan Kochpatcharin**, Head of the Design Infrastructure Management Division at TSMC. "Our partnership with MosChip expands TSMC's design ecosystem and enables our mutual customers to achieve next-generation design success and quickly launch their differentiated products to market."





# **SEMICONDUCTOR IP**

# MIXED SIGNAL IP AND RELATED SERVICES





# ANALOG IP CUSTOMIZATION SERVICES

Nodes		
TSMC	SAMSUNG	GLOBAL FOUNDRY
FinFET 3nm, 5nm, 6nm and 7nm	4nm	12LP
12FFC	5nm	14FF
28nm HPC, HPC+	12nm	22 FDX
40LP, 180nm		40nm, 55nm

CUSTOMER PROJECTS	INTERNAL PLATFORMS
DISPLAY PORT/HDMI SerDes (10G)	Long Range SerDes (16G )
Multi-Protocol SerDes (6.4G)	Short Range SerDes (10G)
DDR4, GDDR5 PHY	ARM HSSTP PHY (12.5G)
TOUCH SENSOR IMAGE SENSOR	ADC
Serial Lite SerDes (2.5G)	LVDS IO, PLL

## Design Tools



## Layout Tools



## Other Tools



## 50+ Engineers

- Capable of providing Complex IP Porting solutions like Serdes, DDR
- Experience in working with Latest nodes in TSMC and Samsung
- Recognized TSMC Partner (TSMC DCA Partner)
- Adheres to strict IP Development Methodology
- Follows established CAD Flows and Methodology
- Adherence to ISO Standards, ISO9001:2015 Certified Company
- Professional Program Management and Status Updates

# MOSCHIP SERDES IP

[Phy product standards' overview]

Name	Standards	PCS	Data Rate per Lane (Gbps)	Comments
PCIe Gen 1	PCIe 1.1	PIPE	2.5	<ul style="list-style-type: none"> <li>Endpoint or Root Complex</li> <li>PIPE includes skip insertion, deletion</li> <li>PCIe power savings modes</li> </ul>
PCIe Gen 2	PCIe 1.1	PIPE	2.5	<ul style="list-style-type: none"> <li>Endpoint or Root Complex</li> <li>PIPE includes skip insertion, deletion</li> <li>PCIe power savings modes</li> <li>Port bifurcation support</li> </ul>
	PCIe 2.1	PIPE	5.0	
PCIe Gen 3	PCIe 3.1/2.1/1.1	Partners	8.0	<ul style="list-style-type: none"> <li>Endpoint or Root Complex</li> <li>PCIe standard multi-lane interface</li> </ul>
XAUI	XAUI, CX4, KX4	Customer	2.4 - 3.2 / 1.2 - 1.6	<ul style="list-style-type: none"> <li>Generic backplane uses</li> </ul>
CEI-6	CEI-6, XAUI, CX4, KX4	Customer	4.8 - 6.4 / 2.4 - 3.2 / 1.2 - 1.6	<ul style="list-style-type: none"> <li>Generic backplane uses</li> </ul>
SATA I/II/III	SATA I/II	SATA	1.5/3.0	<ul style="list-style-type: none"> <li>Advanced frequency offset (PPM) compensation for +0 / -0.5% SSC</li> </ul>
	SATA III	SATA	6.0	
Switchable	Multiple	Multiple	Multiple	<ul style="list-style-type: none"> <li>Switchable between 2 or 3 standards</li> <li>Separate interface for each standard</li> </ul>
ARM HSSTP	HSSTP 6.0	Aurora Link	6.25 / 12.5	<ul style="list-style-type: none"> <li>ARM HSSTP PHY along with Link Layer as a single macro</li> </ul>
PCIe Gen4	PCIe 4.0	Partners	16	<ul style="list-style-type: none"> <li>Test silicon functional and in CHAR/Debug</li> </ul>
Seriallite PHY	IEEE149.1	PCS	3.125	<ul style="list-style-type: none"> <li>chip2chip, board2board, shelf2shelf or backplane</li> </ul>
10/100/1000 Ethernet	IEEE802.3	PCS	1	<ul style="list-style-type: none"> <li>AFE Block in development</li> </ul>
USR/VSR/SR		PCS	10	<ul style="list-style-type: none"> <li>Chip to Chip SerDes. In Development</li> </ul>

# MOSCHIP DIGITAL IP

## USB

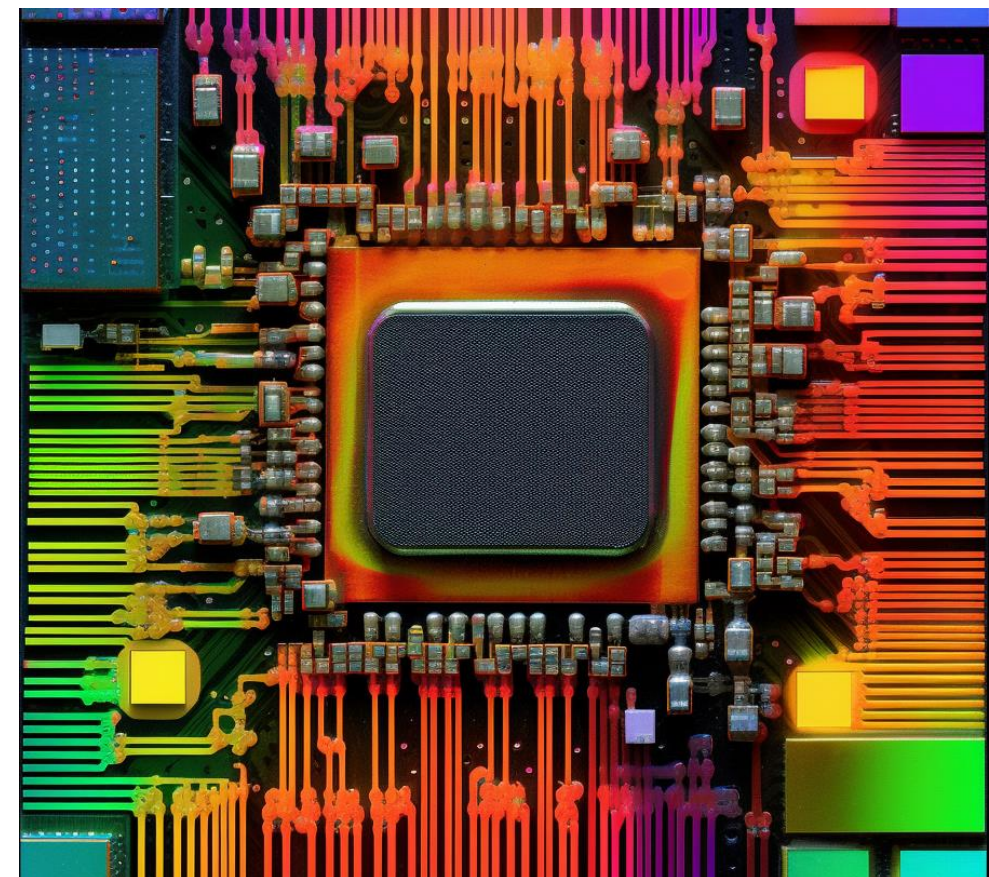
- Host Controller
- Device Controller
- Retimer
- Dual-Role-Device

## SECURITY

- Secure Hash Algorithms (SHA1, SHA2, SHA3)
- Reed-Solomon based FEC
- Reed-Solomon based Erasure (Static & Dynamic)

## ENCRYPTION

- Advanced Encryption Standard (AES 128, AES 256)
- XTS-AES



**Best in class  
performance**

**Up to 20% Better  
throughput**

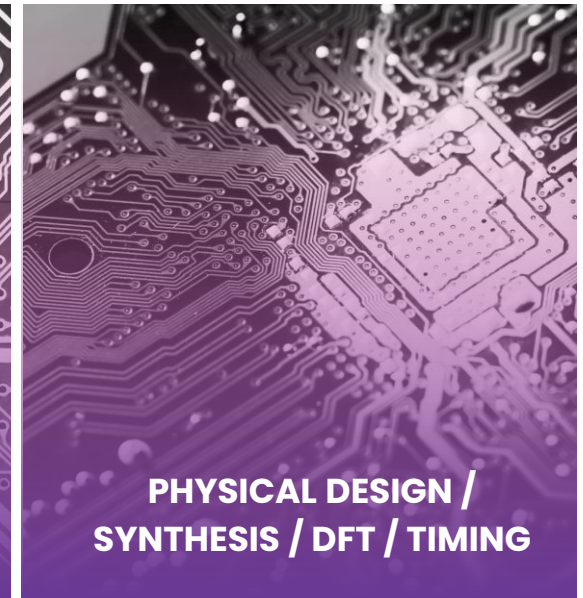
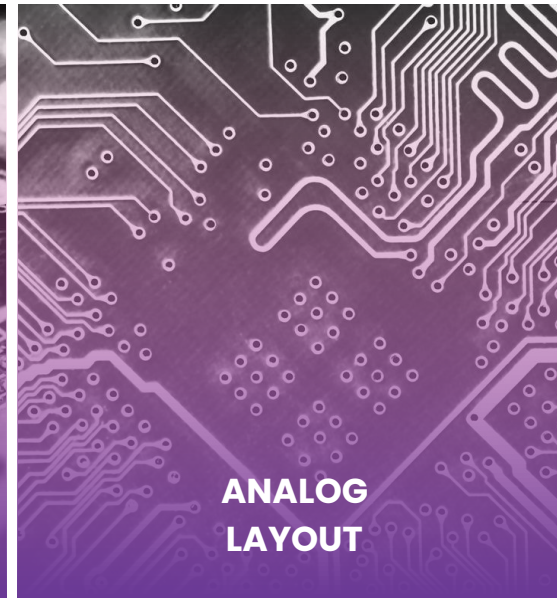
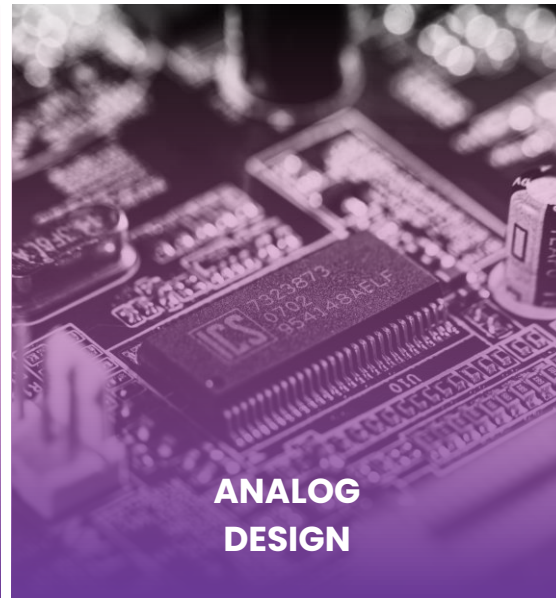
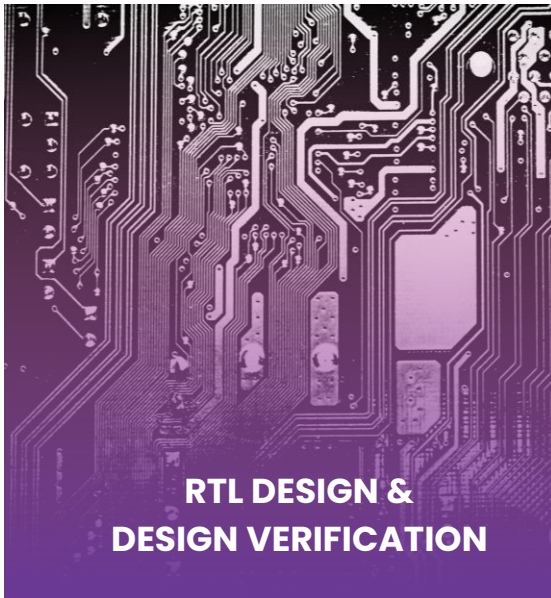
**Platform  
Independent**



# **SEMICONDUCTOR DESIGN SERVICES**



# OVERVIEW OF SEMICONDUCTOR GROUP



- Achieved “**first-pass silicon success**” across **400+** tape-outs
- Expertise ranging from **500nm** to the latest **3/5/6/7 /10 /14 /16 nm FinFET & SOI process nodes**
- Very strong **RTL Design, Design Verification, Physical Design, Analog Design, and Analog Layout** team with over 15 years of average experience in the senior team
- Engaged in complex chip designs extending to **100+ million gates**
- Highest level of training & experience on state-of-the-art technologies
- Design Houses in **Hyderabad, Bengaluru, Ahmedabad, Pune** and **Santa Clara, USA**



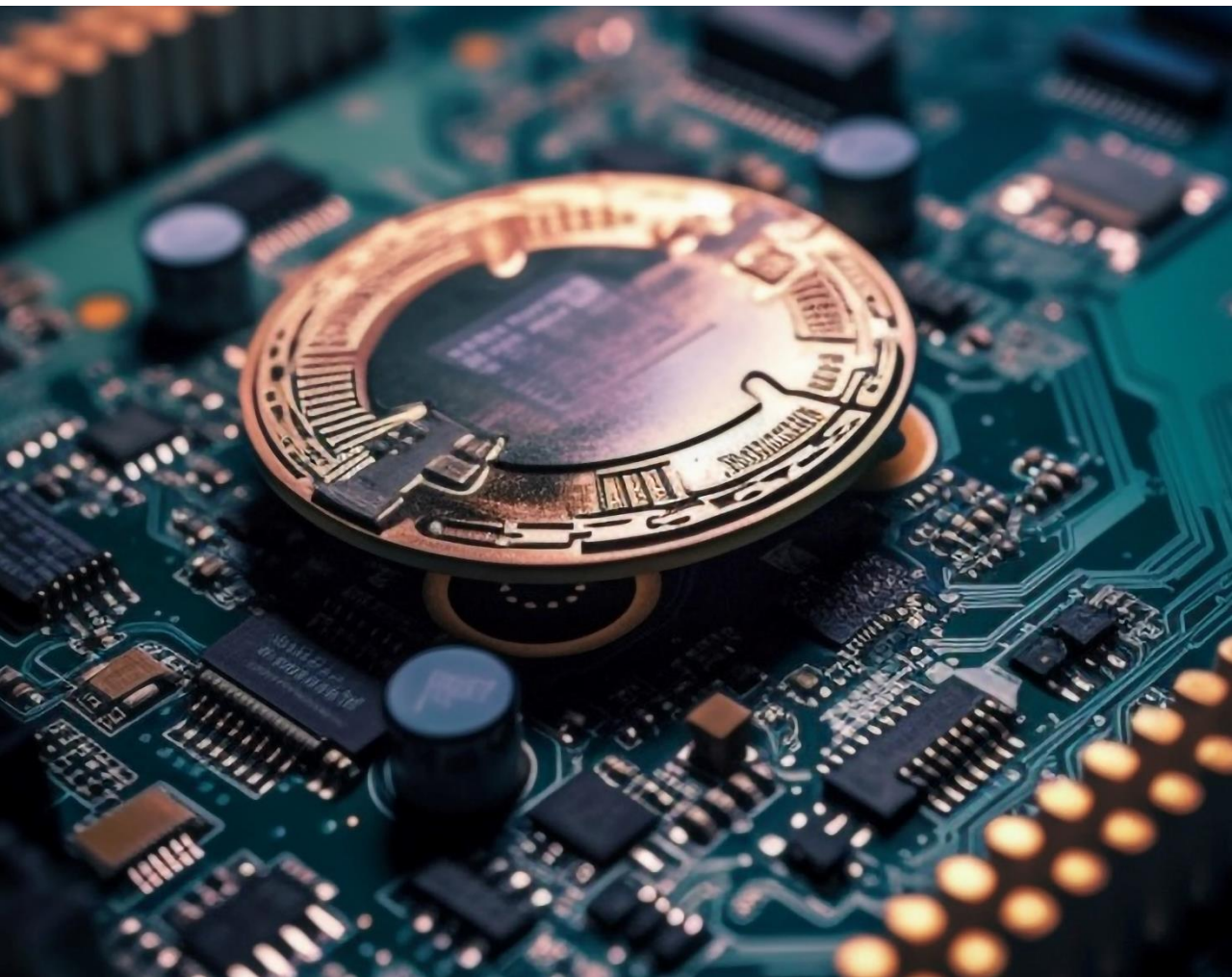
**900+ VLSI Engineers**



**400+ Tape-outs  
with 100% First-Pass  
Silicon Success**



**Engagement Model  
ODC | T&M | Turnkey**



# RTL DESIGN & DESIGN VERIFICATION SERVICES



**18+**  
**AVG.EXP. OF**  
**LEADERSHIP**



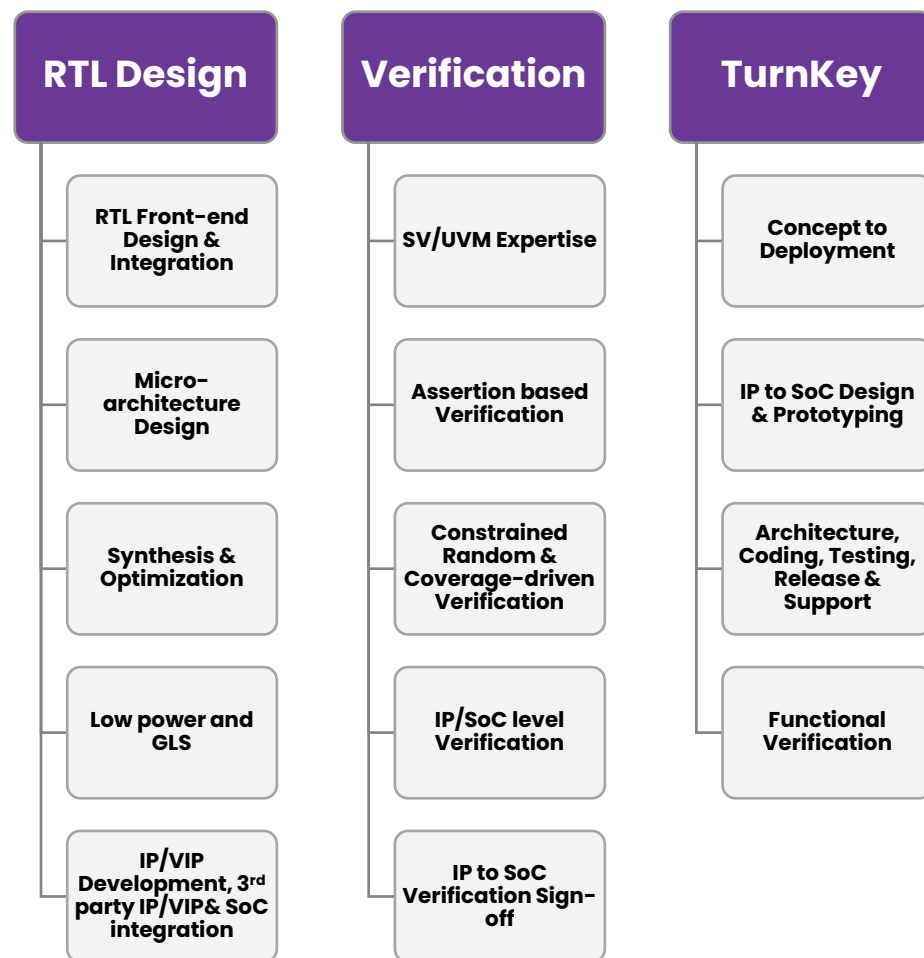
**100+**  
**TAPE-OUTS**



**200+**  
**ENGINEERS**



# RTL DESIGN & VERIFICATION



PROCESSOR	TOOLS	HIGHLIGHTS	LANGUAGES
   	  	<ul style="list-style-type: none"> <li>★ Digital IPs/Subsystem – GCC, and Arite core</li> <li>★ Mixed signaling IPs – Tejas, Brain beats and Borealis</li> <li>★ Turnkey project – Matrix SoC</li> </ul>	 

# TECHNOLOGY EXPERTISE

## IP Interfaces / Protocols



### Ethernet

HDMI | SATA  
SAS | CAN  
AXI/APB  
xHCI | PIPE  
UTMI+ULPI  
SPI | I2C  
Interlaken  
MIPI | DP

## Verification Tools

Questa | Incisive  
VCS | Jasper  
QuestaFormal  
Xcellium  
Simvision  
Visualizer  
Codelink Verdi  
Formality  
FormalPro  
QuestaSLEC  
Conformal

## Languages & Methodology



## Scripts



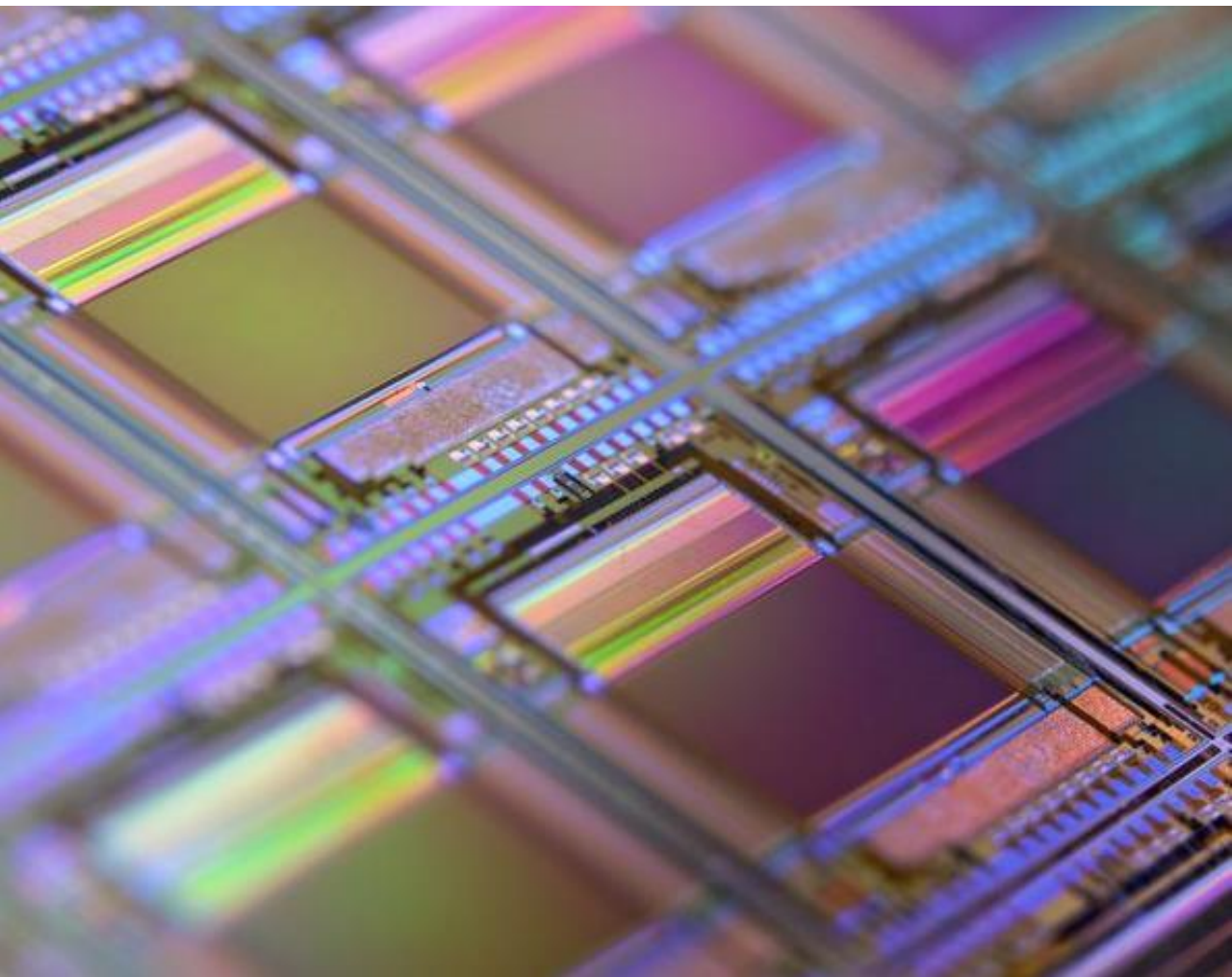
Shell

## Prototype Platforms



cadence





# ANALOG LAYOUT SERVICES



**18+**  
**AVG.EXP. OF**  
**LEADERSHIP**



**150+**  
**TAPE-OUTS**



**250+**  
**ENGINEERS**

# ANALOG LAYOUT SERVICES

## Technologies

- TSMC – N3E | N3P | 5FF | 6FF | 7FF | 12FF | 16FF
- TSMC – 22nm, 28nm, 180nm
- SAMSUNG – 3nm, 4nm, 5nm, 7nm
- GF – 14nm, 12nm, 22nm, 40nm, 55nm, 65nm

## Expertise

- High Speed Serdes up to 112Gbps – Very Short Reach or Extra Short Reach Serdes of 112Gbps data rate, PCIe6 Gen Protocols
- Power Management Layouts – LDO, BGR, SMPS, Bias blocks, Buck Boost converters, etc.
- I/O cells – GPIOs, LVDS, DDR Ios and GDDR IOs
- Data Converters – ADC, DAC with different architectures (Pipeline, SAR ADC, Flash ADC, Current steering DAC and R-2R ladder DAC)
- RF Layouts
- Memory Layouts – Register files, Dense RAM, Cache Memory, CAM Memory
- Clock Generators – Phase Locked Loop, Delay Locked Loop

### UNVEILING

- ★ Ready to Tape-out the Chip in 3nm
- ★ TSMC 22nm Ultra Low Leakage (ULL) AIoT Edge AI SoC for NTU, ASTAR & EMass.ai [RTL-Silicon]

### TOOLS

cā dence<sup>®</sup> Mentor  
Graphics<sup>®</sup>  
Ansys<sup>®</sup> SYNOPSYS<sup>®</sup>

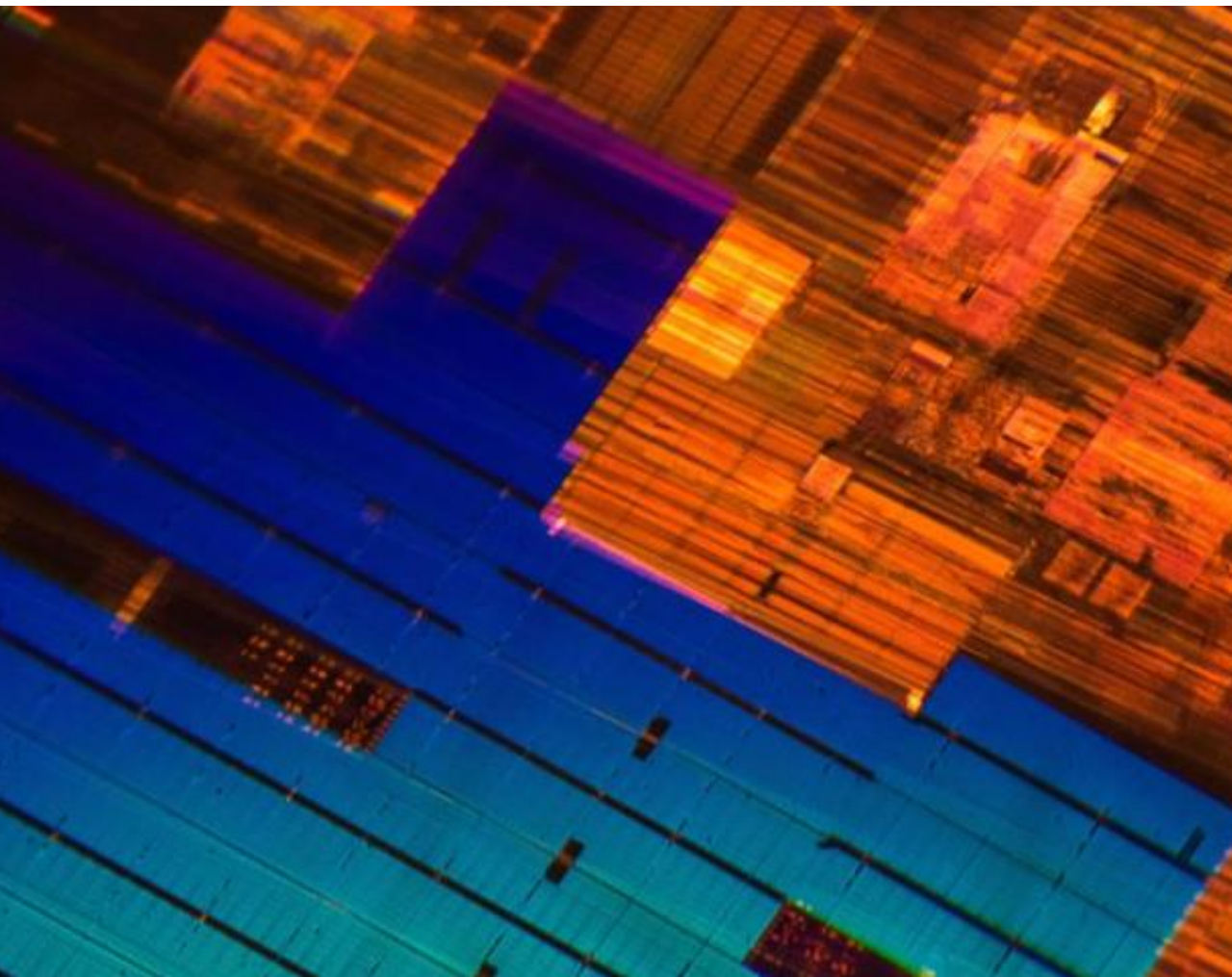
### HIGHLIGHTS

- ★ SerDes – Up-to 112GBPS
- ★ SerDes – PCIe5 & PCIe4 with Multiprotocol support
- ★ SerDes – Up-to 112GBPS

# ANALOG LAYOUT – IP DETAILS

PRODUCT	TECHNOLOGY	SPECIFICATION	APPLICATION
XSR SerDes	TSMC N5	112 Gbps	Networking/Servers
PCIe Gen6	TSMC N5	64 Gbps	Networking / Servers
DDRIO	TSMC N3	4.8 Gbps - 5.6 Gbps	Memory Applications
DDRIO	TSMC 5G	4.8 Gbps - 5.6 Gbps	Memory Applications
DDRIO	Samsung 5nm	4.8 Gbps - 5.6 Gbps	Memory Applications
Graphical DDR	TSMC 12FFC	12 Gbps	Memory Applications
PMU / PMW Controllers	TSMC180		Laptop / Servers
High Precision Oscillators	TSMC N55	Speed of 5Ghz	Aerospace, Defense, Automotive, Electronics, Mobile & IoT
Clock Generator	TSMC N3	Speed of 5Ghz	Processors
Smart Electrical Meter IC	TSMC 180	45-55Hz, 1 Phase / 3 Phase	Electric Measuring Applications





# PHYSICAL DESIGN SERVICES



**20+**  
**AVG.EXP. OF**  
**LEADERSHIP**



**150+**  
**TAPE-OUTS**



**400+**  
**ENGINEERS**



# PHYSICAL DESIGN SERVICES

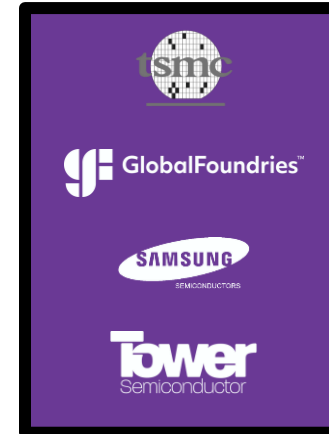
## EXPERTISE

- Block-Level Place & route
- Timing Closure & Static Timing Analysis
- Multiple Domain Clock-Tree Synthesis
- Physical Verification (DRC/ERC/LVS)
- EM-IR Drop Analysis, SI Closure
- Chip-Integration
- Logic Synthesis & Physical Synthesis
- Low Power Expertise – Clock Gating, Multi-Vt, Voltage Islands, Power Gating

## FLIP-CHIP EXPERTISE

- O-ring design
- Bump Assignment work with Package team and Finalize
- Customer Designed Bump/RDL integration to chip level
- RDL Design and Routing
- Help Customers to decide Metal Stack
- Bumps and Package

### TECHNOLOGIES



### LEADERSHIP HISTORY



### HIGHLIGHTS

- ★ Full-Chip Integration | Floor-Plan | Analog Integration | IP-Integration
- ★ Full-Chip Pin-Assignment & Budgeting | Power-Grid Design & Analysis
- ★ Clock-Design | timing Closure | Physical Verification & EM-IR
- ★ DDR-Integration using new generation timing libraries (LVF)

### TOOLS



# SUMMARY OF RECENT & RELEVANT SAMPLE PD PROJECTS

PROCESS	APPLICATION	DESIGN FEATURES	TEAM SIZE PD ENGINEERS	FLOW	DURATION MONTHS	STATUS
TSMC 5nm	Client SoC	~ 75M gates, ~ 30 Blocks	15	Customer	12	In Progress
TSMC 6nm	Client SoC	~ 190M gates, ~ 66 Blocks	35	Customer	12	Taped-out
TSMC 6nm	Client SoC	~ 70M gates, 20 Blocks	15	Customer	7	Taped-out
TSMC 6nm	GPU	~ 365M gates, ~ 100 Blocks	50	Customer	11	In Progress
TSMC 7nm	GPU	~ 275Mgates, ~ 80 Blocks	44	Customer	12	Functional
TSMC 16nmFFP	Video Game	~ 22M gates, 25 Blocks	10	Customer	10	Production
GF 14LLP	Graphics	~ 40M gates, 30 blocks	11	Customer	12	Production
TSMC 28nm HPC+	Networking	~ 103M gates, 14 Blocks	12	MosChip	15	Production
TSMC 40nm G	Networking	~ 12M gates, 8 Blocks	8	MosChip	7	Production
GF 14nm HPP	Ethernet	~ 28M gates, 9 Blocks	6	MosChip	7	Production
TSMC 28nm HPC+	GSP	~ 93M gates, 3 (Unique) Blocks	6	MosChip	12	Functional (PoC)
Samsung 14nmLPP	GSP	~ 120M gates, 3 (Unique) Blocks	6	MosChip	12	Production
TSMC 22nm ULL	Edge SoC	~ 2.2M gates, Flat Chip	3	MosChip	4	Bring-up



# EMBEDDED SYSTEMS, SOFTWARE & PRODUCT DESIGN SERVICES

# OVERVIEW OF EMBEDDED GROUP

MosChip offers various Embedded Product Design Services such as:

- **Embedded Product Design:**
  - Turn-key solutions with System Design, Software Development, FPGA Integration, Bring-up, Validation & Manufacturing / Production Enablement & Improvements, Formfactor Designs for Custom or COTS Enclosures
- **Embedded System Software Development:**
  - BSP / OS Porting, Device Drivers, Integration, Bring-up, Validation & Maintenance with Version Control
- **Complex & High-Speed System Design:**
  - System Architecture / Schematic Design, PCB Layout, SI / PI / Thermal Sims, Bring-up, Validation, Design updates with Version Control, Prototyping and Manufacturing

## OS PORTING & BOARD SUPPORT PACKAGE (BSP)



## PROCESSORS



## 400+ Engineers

- 23+ Years Track Record with 500+ projects in Embedded Software Development & System Design
- Enabling solutions from Concept > POC > Production > Field Enablement
- Flexible engagement models in catering to Semiconductors, Defence, Medical, Storage, Computing, Consumer & IoT Product Segments
- Proven workflow of multiple designs with different Clients at different geo-graphic locations & product segments
- Engineering Partners for Indian Defence Labs

## MULTIMEDIA

Display / Video / Audio Codecs & Controllers HDMI, MIPI, CSI, DSI, Touch Screen, LCD/LVDS

## PERIPHERALS

DMA, I2C, I2S, McBSP, UART, MMC/SD, SPI, eMMC, SDIO, NAND, NOR, DDR3/DDR4, PMIC & Power Management

## CONNECTIVITY

USB, PCI/PCIe, WLAN, IrDA, Ethernet, ZigBee, BT/BLE, GPS, NFC

# EMBEDDED SOFTWARE – SKILL SUMMARY

<b>APPLICATIONS</b>	<ul style="list-style-type: none"> <li>• GUI Design for Si Bring-up / Validation, Configuration &amp; Diagnostics</li> <li>• Custom Applications – USB Over Ethernet, Serial Over Ethernet, NAS etc.,</li> <li>• Low Level Firmware and Post</li> </ul>
<b>MIDDLE WARE</b>	<ul style="list-style-type: none"> <li>• Multimedia – Display, Audio / Video Codecs &amp; Controllers, HDMI, MIPI – CSI / DSI, Touch Screen, LCD/LVDS</li> <li>• Power Management</li> <li>• Connectivity – BT, WIFI, NFC, Zigbee &amp; GPS / GNSS</li> </ul>
<b>SYSTEM SOFTWARE</b>	<ul style="list-style-type: none"> <li>• PBL, Uboot, XBL (UEFI), POST</li> <li>• BSP, Board Bring-up</li> <li>• Kernel &amp; Device Drivers (I2C, I2S, UART, MMC/SD, SPI, eMMC, SDIO, NAND, NOR, DDR, USB, PCI/PCIe, WLAN, Ethernet)</li> </ul>
<b>OPERATING SYSTEMS</b>	<ul style="list-style-type: none"> <li>• Linux</li> <li>• Android</li> <li>• Windows</li> <li>• RTOS – Vx Works, FreeRTOS</li> <li>• Lattice SenseAI</li> <li>• Arm Mbed</li> </ul>
<b>PLATFORMS</b>	<ul style="list-style-type: none"> <li>• ARM, Freescale, TI, Samsung, Qualcomm, Xilinx, Lattice. Broadcom, Intel, Microchip Processors</li> </ul>



# EMBEDDED SOFTWARE CAPABILITIES



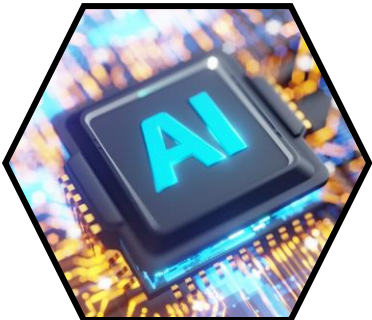
**Platform  
Engineering**



**Multimedia  
Engineering**



**Digital  
Engineering**



**AI  
Engineering**



**Quality  
Engineering**



**Network  
Engineering**



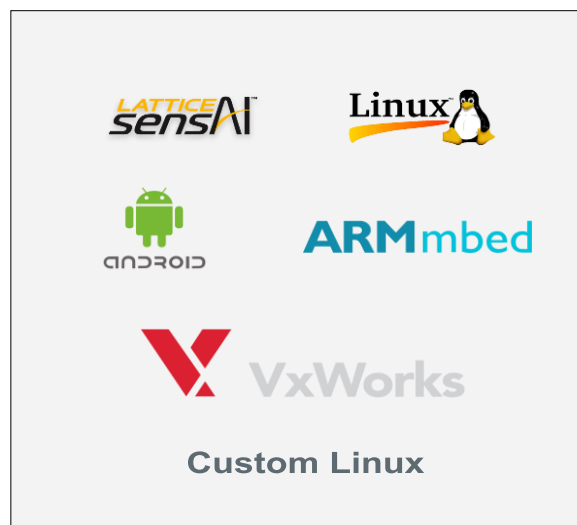
# PLATFORM ENGINEERING

FPGA DESIGN	EMBEDDED SYSTEMS & SOFTWARE DEVELOPMENT	SECURITY
<ul style="list-style-type: none"> <li>• RTL Front-End Design &amp; Integration</li> <li>• FPGA Software &amp; Systems Bring-up</li> <li>• FPGA Acceleration Solutions</li> <li>• Interface &amp; IP Integration</li> <li>• Reference Design</li> </ul>	<ul style="list-style-type: none"> <li>• Platform Enablement</li> <li>• Firmware &amp; Driver Development</li> <li>• BSP &amp; Board Bring-up OS Porting &amp; Bootloader Optimization</li> <li>• Middleware Integration</li> <li>• Product Re-Engineering &amp; Sustenance</li> </ul>	<ul style="list-style-type: none"> <li>• Secure Platform Root-of-Trust (PROT)</li> <li>• Fuzz &amp; Penetration Testing</li> <li>• Edge to Cloud Security</li> <li>• Device &amp; Data Security Lifecycle Management</li> <li>• Identity &amp; Access Management</li> </ul>

## Device Tools & Frameworks



## Operating Systems



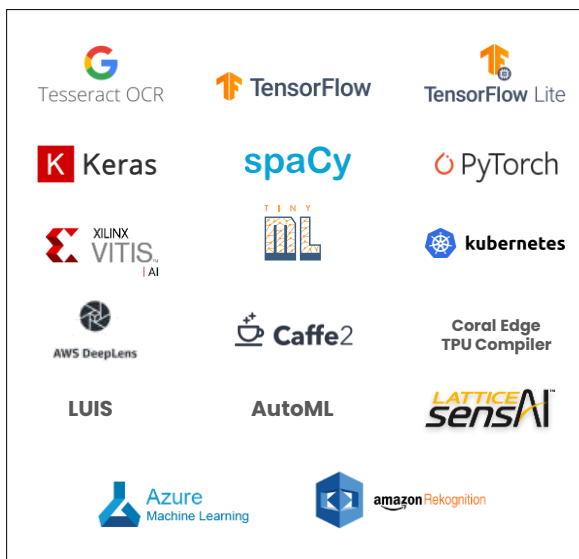
## Edge Tools & Frameworks



# AI ENGINEERING

COMPUTER VISION	ML LIFECYCLE MANAGEMENT	COGNITIVE COMPUTING	AI/FPGA ACCELERATION SOLUTIONS
<ul style="list-style-type: none"> <li>Machine &amp; Computer Vision Algorithms</li> <li>Object Detection, Identification &amp; Visual Perception</li> <li>Image Capture &amp; Optimization</li> <li>Vision Analytics &amp; Processing</li> <li>Optical Character Recognition</li> </ul>	<ul style="list-style-type: none"> <li>MLOps – Automated ML Pipeline Deployment</li> <li>Model Designing, Optimization, Testing &amp; Porting</li> <li>Inference Engines &amp; Metrics</li> <li>ML Transfer Learning Framework</li> <li>Data Augmentation &amp; Annotation</li> </ul>	<ul style="list-style-type: none"> <li>Deep Learning &amp; Neural Networks</li> <li>AI/ML on Edge &amp; Cloud</li> <li>ML Application Acceleration</li> <li>Cross Platform Porting &amp; Integration</li> <li>Natural Language Processing (NLP)</li> </ul>	<ul style="list-style-type: none"> <li>Scene Detection &amp; Text Analytics</li> <li>Predictive Analytics</li> <li>Audio Analytics &amp; Key-phrase Detection</li> <li>Face Recognition</li> <li>ML Reference Designs &amp; POC</li> </ul>

## AI Tools & Frameworks



## Architectures



# MULTIMEDIA ENGINEERING

AUDIO SOLUTIONS	VIDEO SOLUTIONS	EMBEDDED & MULTIMEDIA SYSTEMS	CAMERA ENABLED SOLUTIONS	IMMERSIVE SOLUTIONS
<ul style="list-style-type: none"> <li>Audio Codec Engineering</li> <li>Audio Command Detection</li> <li>Audio Algorithm Development</li> <li>ALSA Driver Development</li> </ul>	<ul style="list-style-type: none"> <li>Video Codec Engineering</li> <li>Surveillance &amp; DVR</li> <li>Video Analysis &amp; Validation</li> <li>VoD &amp; Media Streaming</li> <li>Image Stitching</li> </ul>	<ul style="list-style-type: none"> <li>Multimedia Framework Integration</li> <li>Multimedia Systems &amp; SDK Development</li> <li>Android Multimedia &amp; HAL Development</li> <li>OpenVX Acceleration</li> <li>Media Infotainment Systems</li> </ul>	<ul style="list-style-type: none"> <li>Smart Camera Applications</li> <li>Firmware &amp; Driver Development</li> <li>Image Signal Processing (ISP)</li> <li>Camera Framework Integration</li> </ul>	<ul style="list-style-type: none"> <li>AR/VR application development</li> <li>VR gadget feature development</li> <li>VR streaming on Wi-Fi</li> <li>Open Standard based VR/AR</li> <li>VR on Cloud</li> </ul>

Audio & Speech Codecs	Video & Image Codecs	Platforms	Architectures	Frameworks	Streaming & Screen-Casting
<p><b>AMR-NB/WB</b></p> <p><b>QCELP</b></p> <p><b>EVRC</b></p>	<p><b>HEVC</b></p> <p><b>H.264</b></p> <p><b>VP8/9</b></p>		<p><b>Multi-core</b></p> <p><b>ARM</b></p> <p><b>DSP</b></p> <p><b>GPUs</b></p>	<p>FastCV</p> <p>OpenVR    V4L2</p> <p><b>Windows Media</b></p> <p><b>OpenMAX IL</b></p> <p><b>DL      DRM</b></p>	<p>Miracast source and sink</p> <p>RTP   SRTP</p> <p>Adaptive Streaming Technologies,</p> <p>MPEG2 TS, WebRTC,</p> <p>Image/Video Analytics</p> <p>Tiling   Stitching</p>

# QUALITY ENGINEERING

DEVICE & EMBEDDED TESTING	QUALITY ASSURANCE & PRODUCT TESTING	DEVOPS & TEST AUTOMATION	ML TESTING	CERTIFICATION, COMPLIANCE & CONSULTING
<ul style="list-style-type: none"> <li>Multimedia, Audio/Video Testing</li> <li>Embedded System &amp; Integration Testing</li> <li>Test Tool Development</li> <li>Network Interface Card Validation</li> <li>Software Toolchain Testing</li> </ul>	<ul style="list-style-type: none"> <li>Performance &amp; Functional Testing</li> <li>Sensor Integration &amp; Interoperability</li> <li>Peripherals &amp; Connectivity testing</li> <li>Connected App/Edge Testing</li> </ul>	<ul style="list-style-type: none"> <li>Continuous Integration, Deployment &amp; Testing</li> <li>Device to Cloud Test Automation</li> <li>Test Automation Frameworks</li> <li>Automation Scripts</li> <li>QA Farms</li> </ul>	<ul style="list-style-type: none"> <li>Dataset &amp; Feature Validation</li> <li>Model Validation &amp; Performance Benchmarking</li> <li>Model Parameters Traceability</li> <li>ML Library Integration Testing</li> <li>Embedded Neural Network Application Testing</li> <li>CNN Compiler Validation</li> </ul>	<ul style="list-style-type: none"> <li>FuSa – ISO 26262</li> <li>AUTOSAR &amp; MISRA-C</li> <li>OpenVX Vision Library Conformance</li> <li>Tools/Frameworks Assessment &amp; Integration Support</li> <li>Feasibility Analysis</li> <li>Test Lab Setup Advisory</li> </ul>

Automation Frameworks	Test Management	Performance/Load Testing	Version Control	Networking	In-House QA Tool
Jenkins Selenium appium python™ TestNG Robot Framework	TestRail JIRA TestLink Rational Quality Manager	APACHE JMeter™ LOCUST MONKEY TALK	git TortoiseSVN Bitbucket PERFORCE	WIRESHARK NRF SNIFFER	STAF

# DIGITAL ENGINEERING

IOT	MOBILITY	CLOUD
<ul style="list-style-type: none"><li>IoT Device Connectivity</li><li>Gateway Integration &amp; Management</li><li>Digital Twin</li><li>IoT Device Lifecycle Management</li><li>Gateway &amp; Cloud Security</li></ul>	<ul style="list-style-type: none"><li>Mobile App Development</li><li>UX Design</li><li>Mobile Test Automation Framework</li></ul>	<ul style="list-style-type: none"><li>Cloud Migration</li><li>Cloud Design &amp; Architecture</li><li>Cloud Service Integration</li></ul>

## Connectivity



## Web/ Mobile Applications

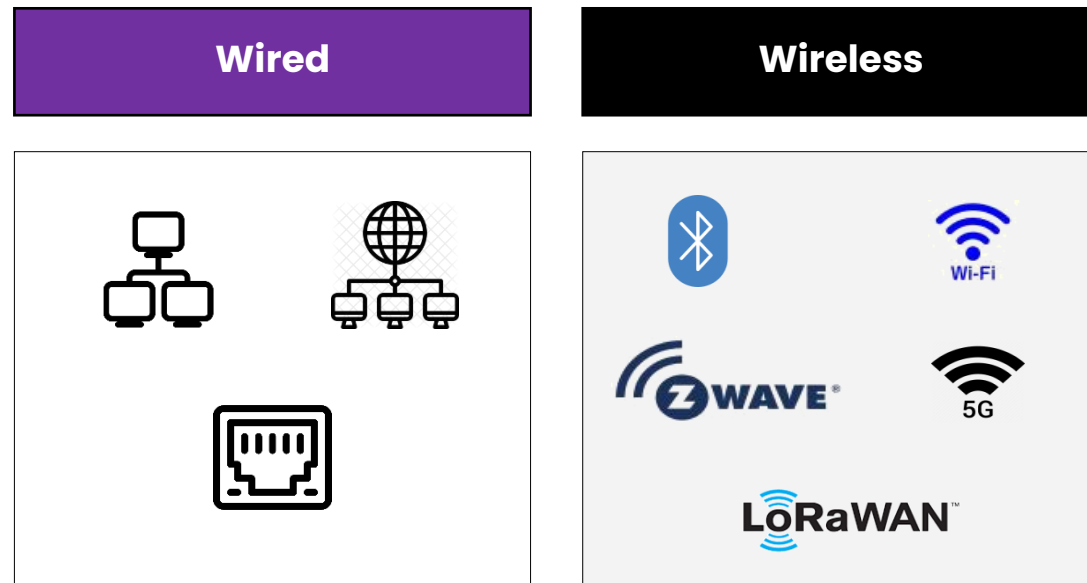


## Cloud



# NETWORK ENGINEERING

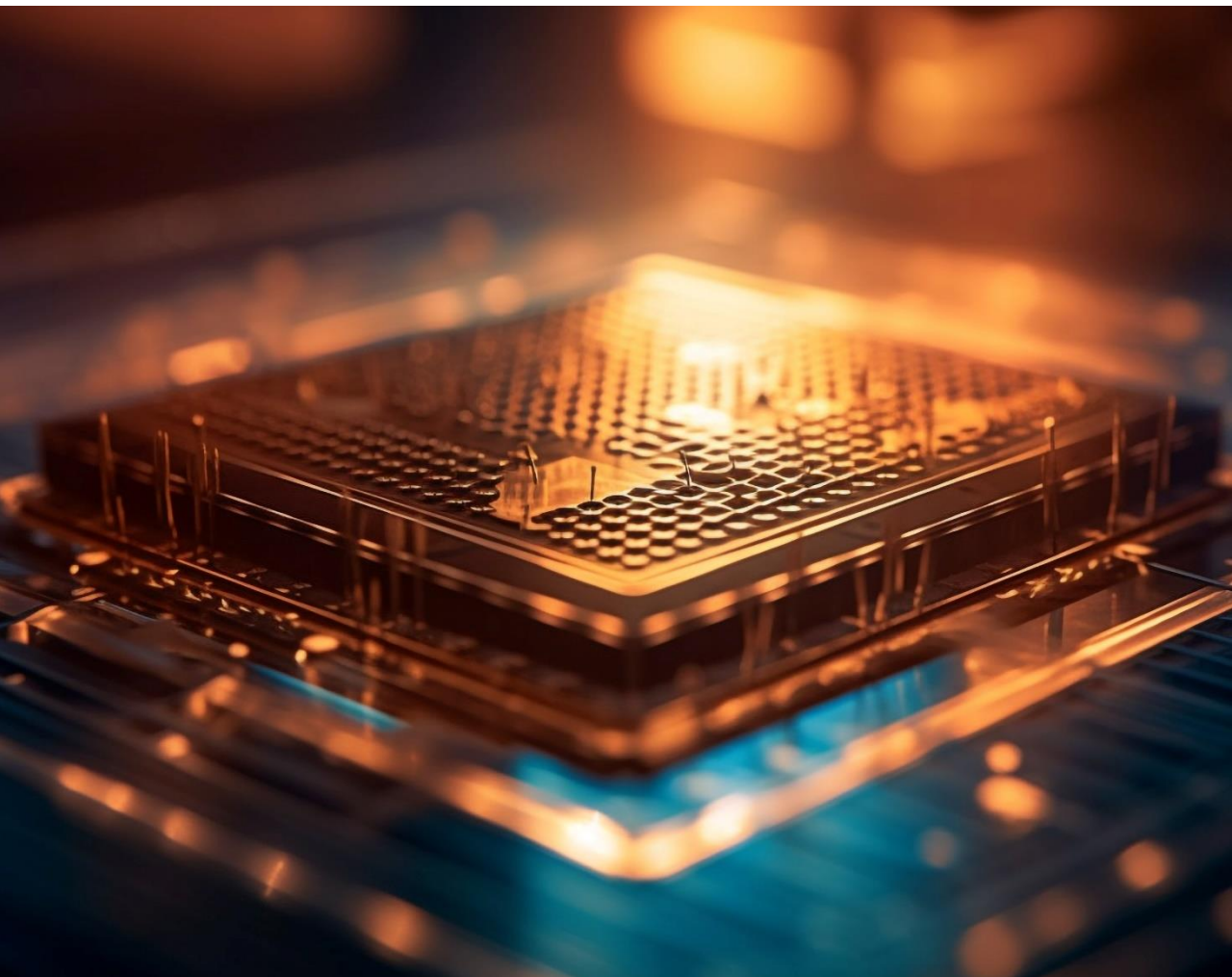
WIRED	WIRELESS
<ul style="list-style-type: none"> <li>• Network Protocol &amp; App Development</li> <li>• Network Stack &amp; Performance Optimization</li> <li>• Network Test Automation</li> <li>• Network Module Integration</li> <li>• Software Defined Networking</li> </ul>	<ul style="list-style-type: none"> <li>• Wireless Solutions (Wi-Fi, BLE, RF)</li> <li>• Customer Premise Equipment</li> <li>• WLAN Drivers</li> <li>• Wi-Fi Co-existence</li> </ul>





# SUMMARY OF RELEVANT SAMPLE EMBEDDED PROJECTS

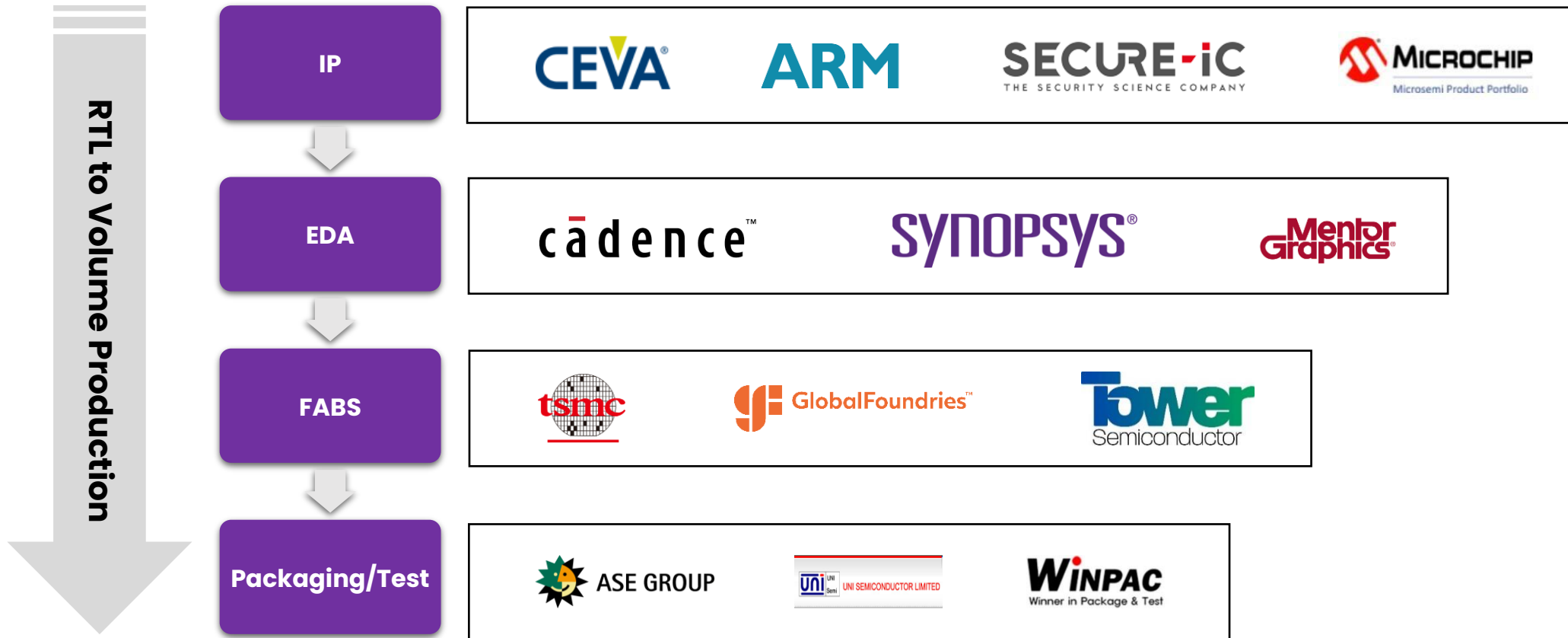
Application	Embedded Service	Status
Home Automation	Firmware development of Wi-Fi module	Completed
Health Monitoring	Firmware development of Wi-Fi & BLE MCU	Completed
Autonomous Driving	ECU software development FuSA (ISO26262), MISRA-C Compliance	Completed
Multimedia	GStreamer plugins development & porting	Completed
Multimedia	DSP based firmware development, audio codecs driver development	Completed
AIML	Data annotation, algorithm training, deployment Computer vision, NLP, OCR, NLP	Completed
Multimedia	ALSA compliant Linux kernel audio driver, Audio firmware feature enhancement	Completed
Camera	Profile & optimize low level u-boot code, A/V subsystem activation at boot-up, design & develop kernel wrapper module	Completed
Inertial Measurement Unit (IMU)	STM firmware development with peripherals like I2C, SPI, USB, etc.	Completed
Wireless	BT-Wi-Fi-LTE Co-existence IP firmware development & validation	Completed



# **SEMICONDUCTOR TURNKEY ASIC**

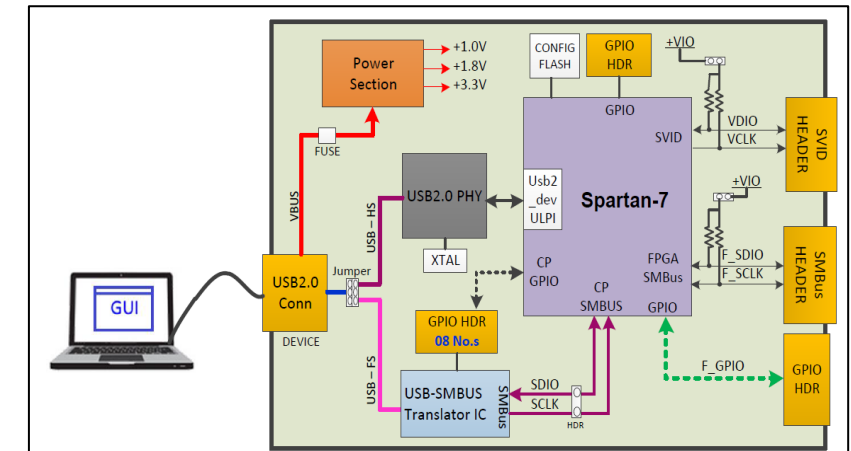
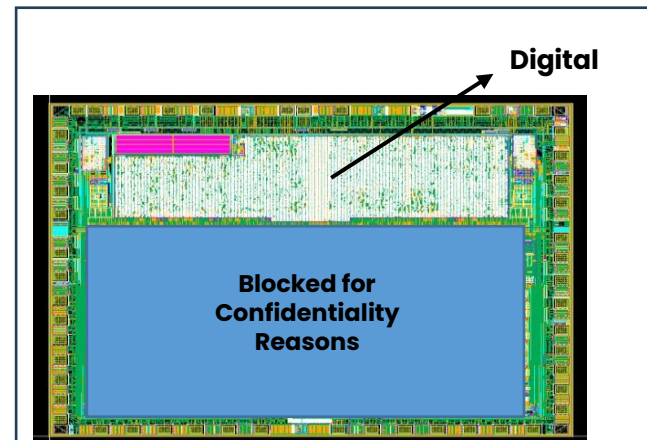
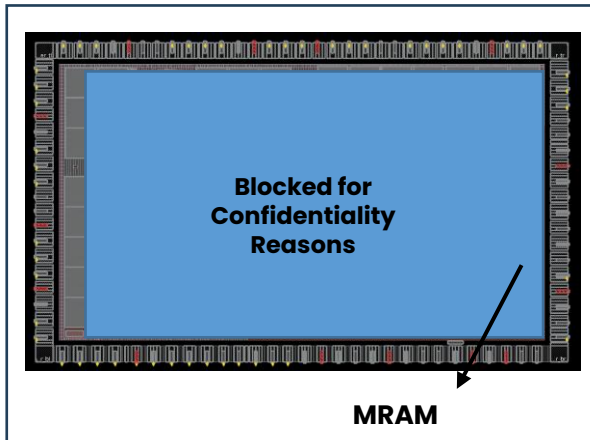
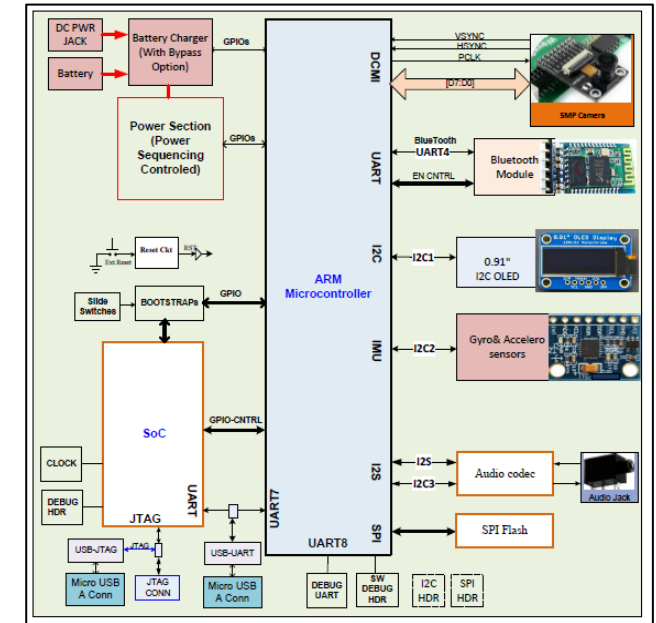
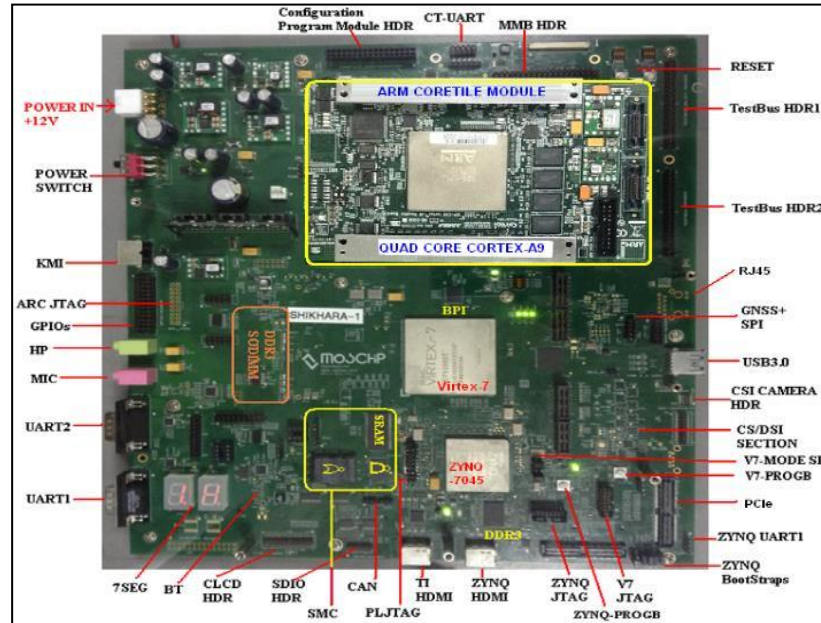
**[RTL TO VOLUME PRODUCTION AND BRING-UP]**

# TURNKEY ASIC ECO PARTNERS

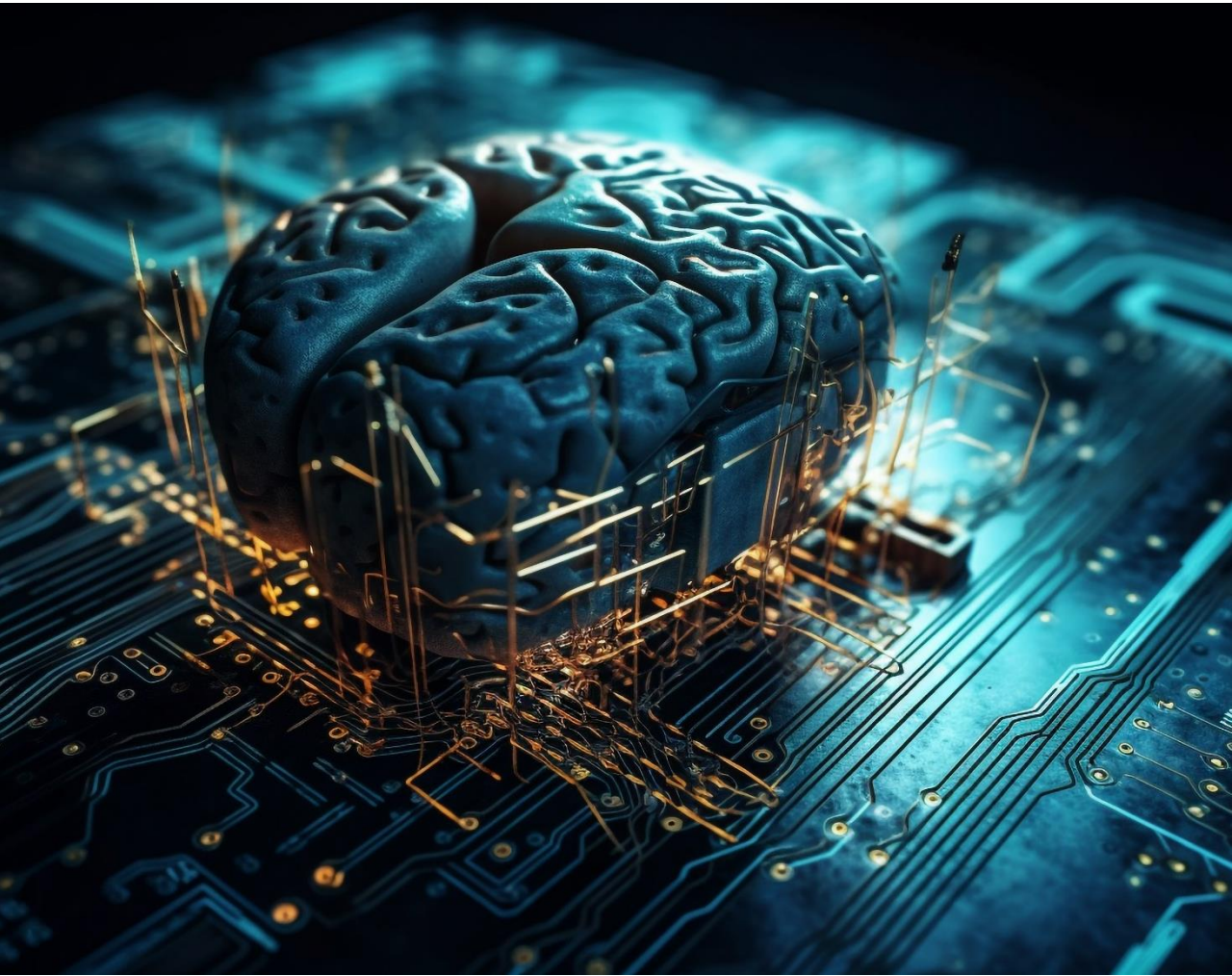


# TURNKEY ASIC

- Turnkey ASIC – Edge SoC
- Turnkey Mixed Signal ASIC – POWER IC
- Edge SoC Reference Platform & Bring-up
- Power IC – Debug Platform Development
- Turnkey ASIC – Matrix (Digital SoC)
- Matrix – FPGA Platform Pre-Silicon Validation
- Matrix – Reference Platform & BSP







# **MosChip ASIC PLATFORMS**

# NNP BASED ASIC PLATFORM FOR EDGE AI

# RISC-V BASED ASIC PLATFORM FOR SMART METERS

## MosChip



# THANK YOU

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